

YTV B3 Series AOI

Benchtop Automated Optical Inspection



- Quick Set-up
- Mega-pixel Color Camera
- High Defect Coverage
- Low False Failure Rate
- Best Price Performance

YESTech's advanced Thin Camera™ technology offers off-line benchtop PCB inspection with exceptional defect coverage. This benchtop system inspects solder joints and verifies correct part assembly enabling users to improve quality and increase throughput.

Programming the B3 is fast and intuitive. Operators typically take less than 30 minutes to create a complete inspection program including solder inspection. The B3 utilizes a standard package library to simplify training and insure program portability across manufacturing lines. Programs created with the B3 are also compatible with YESTech's complete line of AOI systems.

Newly available Fusion Lighting™ and advanced image processing technology integrates several techniques, including color, normalized correlation and rule-base algorithms, to provide complete inspection coverage with an extremely low false failure rate.

The B3 is equally effective for pre / post-reflow or even final assembly inspection. Remote programming maximizes machine utilization and real-time SPC monitoring provides a valuable yield enhancement solution.

- AUTOMATED INSPECTION FOR:**
- **Solder & lead defects**
 - **Component presence and position**
 - **Correct part**
 - **Polarity**
 - **Through-hole parts**
 - **Paste**

YESTech

“World Leader in Automated Optical Inspections and X-Ray Inspection Systems”

SPECIFICATIONS*

Inspection Capabilities	
• Throughput	4 sq. in./ sec.: > 200,000 components per hour
• Maximum Board Size	350mm x 250mm (14 x 10 in.)
• Clearance	2" (50mm) top and bottom
• Minimum Component Size	01005
• Defects Detected	Component: position, missing, wrong, polarity, skew, tombstone Lead: bent, lifted, bridging Solder: open, insufficient, short, solder balls
Software	
• Algorithms	Normalized correlation, OCV, OCR, barcode recognition and rule-based
• CAD Translation Package	CircuitCAM, Unicam, YESTech CAD Utility
• Programming Skill Level	Technician or operator
• Operating System	Windows XP
• Off-line Software	Optional - Rework, Review and Program Creation
• SPC Software	Optional - Real-time local and remote monitoring of first pass yield, defect trends, and machine utilization.
Hardware	
• Lighting	Proprietary Fusion Lighting™ multiangle LED
• Imager	Thin Camera: 25 micron, and / or 12 micron pixel size Resolution 1280 x 1024
• Optics	Telecentric lens (eliminates distortion for more accurate and repeatable measurement and inspection results)
Facilities	
• Power	100-240 VAC, 50/60 Hz, 10 amps
• Footprint	34" x 39" x 17" (864mm x 991mm x 432mm)
• Weight	170 lbs (77 kg)
• Machine Installation	< 1 hour

* Specifications subject to change